Multibeam Adds Industry Leaders to Board of Directors

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SANTA CLARA, Calif., Sept. 18, 2025 – Multibeam Corp. today announced that it has strengthened its global leadership bench by appointing three semiconductor industry executives to its Board of Directors. Elvino da Silveira, David J. Lam, and Amy Leong complete the Board that also includes Multibeam's Chairman & CEO, David K. Lam and President, Ken MacWilliams.

The move caps a 12-month period of accelerating execution for Multibeam marked by the recent closure of a $31M Series B funding round, as well as shipment of the company's first production E-Beam Lithography (EBL) system and rapid development progress on its next-generation 300-mm EBL platform.

"We are so pleased to welcome Elvino, David, and Amy to Multibeam's Board," said David K. Lam, Multibeam Chairman & CEO. "Their expertise and wisdom will be invaluable as we continue to drive innovation across the company and enable customers with an exceptional e-beam lithography system to command leadership in emerging IC markets."

New Board Members

Elvino da Silveira whose four-decade career in the semiconductor capital equipment industry includes extensive experience leading lithography teams. Before retiring, Elvino was General Manager of Onto Innovation's lithography unit where he led the product line transition from wafer level advanced packaging to panel-based heterogeneous packaging applications. Earlier roles included executive positions at Rudolph Technologies, Azores Corporation (acquired by Rudolph), and MRS Technology. He holds a B.S. in Mechanical Engineering from Northeastern University.

David J. Lam brings 25 years of global technology investment and operating experience to the Board. He began his investor career at the Carlyle Group and later served as a General Partner at deep-tech-focused Atlantic Bridge Capital for a decade. Over time, he has funded and advised companies with transformative semiconductor-related technologies ranging from capital equipment, manufacturing, and new materials to integrated circuits and AI data centers. David is a Senior Advisor to BRV Capital Management, a Board Member of SweGaN, and an Advisor to Syntiant and TetraMem. He holds a B.S. in Industrial Engineering and a M.A. in Sociology, both from Stanford University, and an MBA from the MIT Sloan School of Management.

Amy Leong joins Multibeam with more than 28 years of experience in the semiconductor industry, bringing deep expertise in strategic marketing, operations, and governance, as well as semiconductor fabrication and advanced packaging technologies. She currently serves as Senior Advisor to AEM Holdings, a publicly listed company headquartered in Singapore, where she previously held the role of CEO. Prior to AEM, Amy held various executive positions at FormFactor Inc. [NASDAQ: FORM] in California, including SVP, Chief Commercial Officer, General Manager, and Chief Marketing Officer. Her early career began in front-end wafer fabrication engineering at IBM and KLA. Amy has served on the Board of Directors for SkyWater Technology [NASDAQ: SKYT] and continues to contribute to industry advancement through her roles on the Singapore Semiconductor Industry Association Board and the International Semiconductor Executive Summits Advisory

Board. She holds a B.S. in Chemical Engineering from UC Berkeley and an M.S. in Materials Science and Engineering from Stanford University.